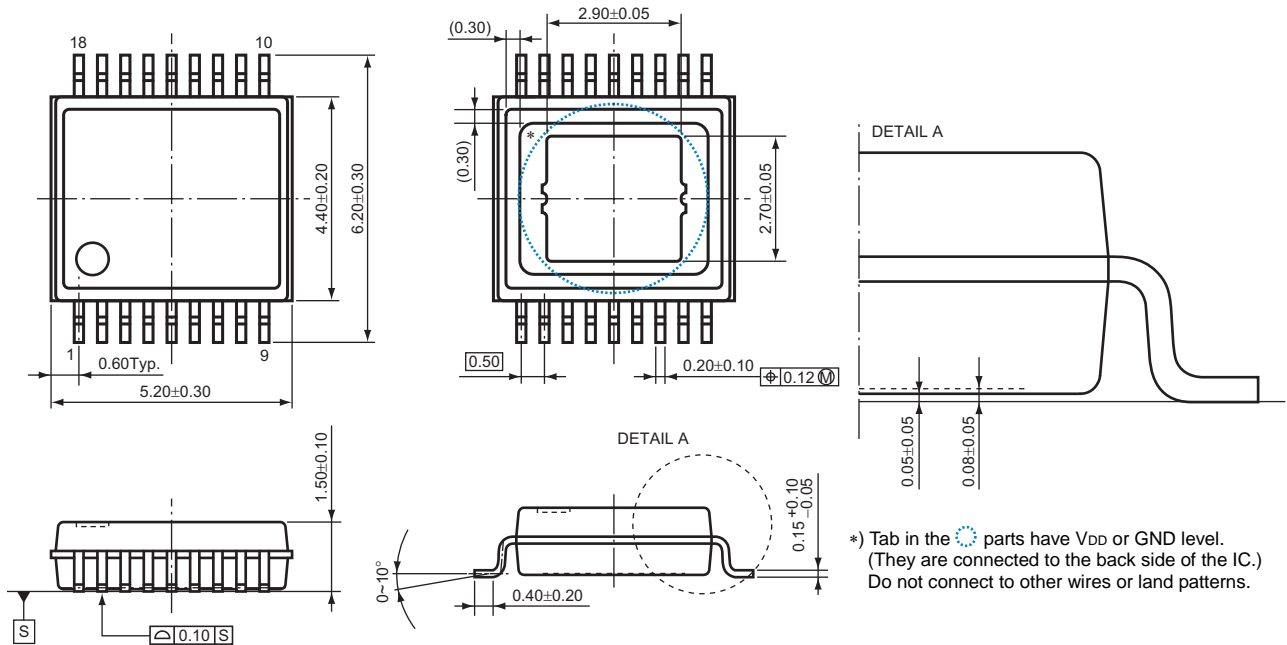


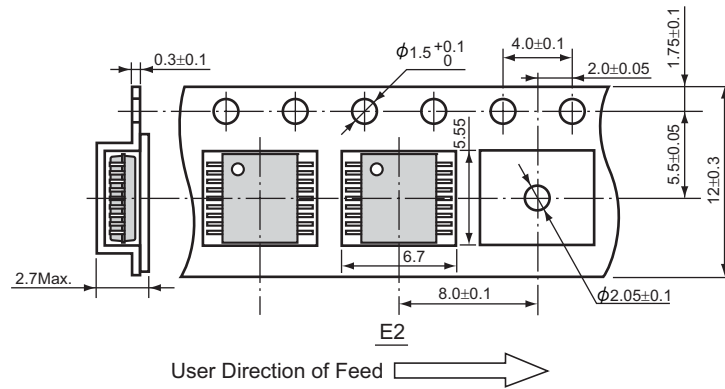
• HSOP-18

Unit: mm

PACKAGE DIMENSIONS

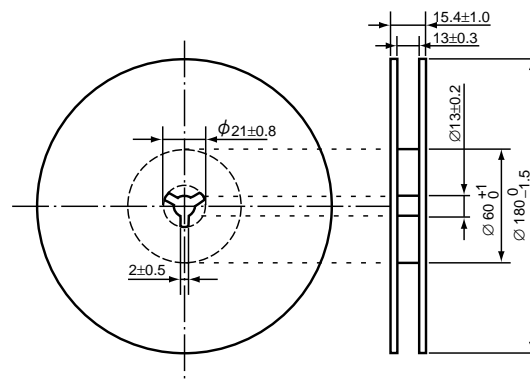


TAPING SPECIFICATION



TAPING REEL DIMENSIONS REUSE REEL (EIAJ-RRM-12Bc)

(1reel=1,000pcs)



POWER DISSIPATION (HSOP-18)

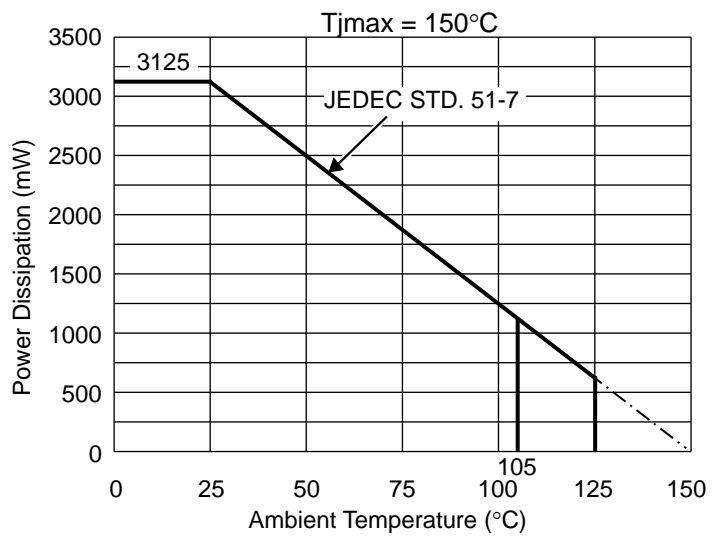
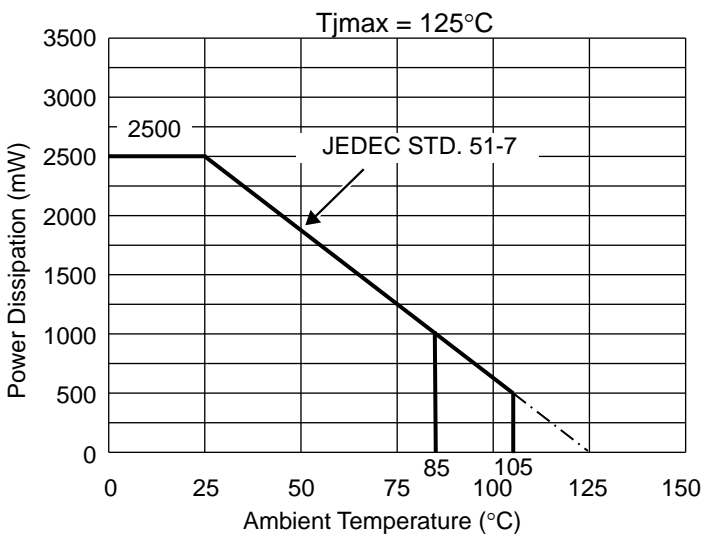
Power Dissipation (P_D) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

Measurement Conditions

	JEDEC STD.51-7 Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (4 layers)
Board Dimensions	76.2 mm × 114.3 mm × 1.6 mm
Copper Ratio	Top side, Back side: 60 mm square, Approx.10% 2nd, 3rd Layer: 74.2 mm square, 100%
Through-holes	φ0.85 mm × 44 pcs

Measurement Results ($T_a = 25^\circ\text{C}$)

	JEDEC STD.51-7 Land Pattern
Power Dissipation	2500 mW ($T_{jmax} = 125^\circ\text{C}$) 3125 mW ($T_{jmax} = 150^\circ\text{C}$)
Thermal Resistance	$\theta_{ja} = 40^\circ\text{C/W}$ $\theta_{jc} = 9^\circ\text{C/W}$



Power Dissipation vs. Ambient Temperature

RECOMMENDED LAND PATTERN

